E4M0060075J2

Silicon Carbide Power MOSFET
E-Series Automotive
N-Channel Enhancement Mode

Features

- 750V SiC MOSFET technology
- Optimized package with separate driver source pin
- 4.7mm of creepage distance between drain and source
- High blocking voltage with low on-resistance
- High-speed switching with low capacitances
- Fast intrinsic diode with low reverse recovery (Q_{rr})
- Halogen free, RoHS compliant
- Automotive Qualified (AEC-Q101) and PPAP Capable

Benefits

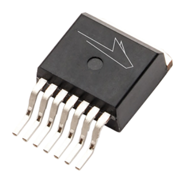
- Reduce switching losses and minimize gate ringing
- Higher system efficiency
- Reduce cooling requirements
- Increase power density
- Increase system switching frequency

Typical Applications

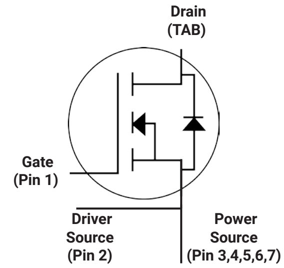
- Motor Control
- EV On Board Battery Chargers (OBC)
- Automotive DC/DC Converters for EV/HEV

Package

Tab
Drain



1 2 3 4 5 6 7



Part Number	Package	Marking
E4M0060075J2	TO-263-7XL	E4M0060075J2

Maximum Ratings (T_C = 25 ˚C unless otherwise specified)

Symbol	Parameter		Value	Unit	Note
V_{DSmax}	Drain - Source Voltage		750	V	
V_{GSmax}	Gate - Source Voltage		-8/+19	V	Note: 1
I_D	Continuous Drain Current, V_{GS} = 15 V	T_C = 25˚C	36	A	Fig. 19 Note: 2
		T_C = 100˚C	27		
$I_{D(pulse)}$	Pulsed Drain Current, Pulse width t_P limited by T_{jmax}		101	A	Fig. 22
P_D	Power Dissipation, T_C=25˚C, T_J = 175 ˚C		131	W	Fig. 20 Note: 2
T_J , T_{stg}	Operating Junction and Storage Temperature		-55 to +175	˚C	
T_L	Solder Temperature, 1.6mm (0.063”) from case for 10s		260	˚C	

Note (1): Recommended turn off / turn on gate voltage V_{GSop} - 4V...0V / +15V
Note (2): Verified by design

Electrical Characteristics (T_C = 25˚C unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	750			V	V_{GS} = 0 V, I_D = 100 μA	
$V_{GS(th)}$	Gate Threshold Voltage	1.8	2.6	3.8	V	V_{DS} = V_{GS}, I_D = 3.67 mA	Fig. 11
			2.1		V	V_{DS} = V_{GS}, I_D = 3.67 mA, T_J = 175ºC	
I_{DSS}	Zero Gate Voltage Drain Current		1	50	μA	V_{DS} = 750 V, V_{GS} = 0 V	
I_{GSS}	Gate-Source Leakage Current		10	250	nA	V_{GS} = 15 V, V_{DS} = 0 V	
$R_{DS(on)}$	Drain-Source On-State Resistance		60	78	mΩ	V_{GS} = 15 V, I_D = 13.4 A	Fig. 4, 5, 6
			87			V_{GS} = 15 V, I_D = 13.4 A, T_J = 175ºC	
g_{fs}	Transconductance		10		S	V_{DS}= 20 V, I_{DS}= 13.4 A	Fig. 7
			8			V_{DS}= 20 V, I_{DS}= 13.4 A, T_J = 175ºC	
C_{iss}	Input Capacitance		1205		pF	V_{GS} = 0 V, V_{DS} = 500 V f = 100 kHz V_{AC} = 25 mV	Fig. 17, 18
C_{oss}	Output Capacitance		77				
C_{rss}	Reverse Transfer Capacitance		8				
E_{oss}	C_{oss} Stored Energy		11		μJ	V_{DS}= 500 V, f = 100 kHz	Fig. 16
$C_{o(er)}$	Effective Output Capacitance (Energy Related)		98		pF	V_{GS} = 0 V, V_{DS} = 0 to 500V	Note: 3
$C_{o(tr)}$	Effective Output Capacitance (Time Related)		136		pF		
E_{ON}	Turn-On Switching Energy (Body Diode FWD)		47		μJ	V_{DS}= 500 V, V_{GS}= -4 V/15 V, I_D= 13.4 A, $R_{G(ext)}$ = 2.5 Ω, L= 135 μH, T_J = 25ºC FWD = Internal Body Diode	Fig. 26, 28
E_{OFF}	Turn-Off Switching Energy (Body Diode FWD)		12				
$t_{d(on)}$	Turn-On Delay Time		8		ns	V_{DD} = 500 V, V_{GS} = -4 V/15 V, I_D = 13.4 A, $R_{G(ext)}$ = 2.5 Ω, L= 135 μH, T_J = 25ºC Timing relative to V_{DS} Inductive load	Fig. 27, 28
t_r	Rise Time		9				
$t_{d(off)}$	Turn-Off Delay Time		16				
t_f	Fall Time		8				
$R_{G(int)}$	Internal Gate Resistance		3.0		Ω	f = 1 MHz, V_{AC} = 25 mV	
Q_{gs}	Gate to Source Charge		15		nC	V_{DS} = 500 V, V_{GS} = -4 V/15 V, I_D = 13.4 A Per IEC60747-8-4 pg 21	Fig. 12
Q_{gd}	Gate to Drain Charge		15				
Q_g	Total Gate Charge		50				

Note (3): $C_{o(er)}$, a lumped capacitance that gives same stored energy as Coss while Vds is rising from 0 to 500V
$C_{o(tr)}$, a lumped capacitance that gives same charging time as Coss while Vds is rising from 0 to 500V

Reverse Diode Characteristics (T_C = 25˚C unless otherwise specified)

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V_{SD}	Diode Forward Voltage	4.8		V	V_{GS} = -4 V, I_{SD} = 6.7 A, T_J = 25 °C	Fig. 8, 9, 10
		4.3		V	V_{GS} = -4 V, I_{SD} = 6.7 A, T_J = 175 °C	
I_S	Continuous Diode Forward Current		22	A	V_{GS} = -4 V, T_C = 25˚C	
$I_{S, pulse}$	Diode pulse Current		101	A	V_{GS} = -4 V, pulse width t_P limited by T_{jmax}	
t_{rr}	Reverse Recover time	11		ns	V_{GS} = -4 V, I_{SD} = 13.4 A, V_R = 500 V di_F/dt = 5410 A/µs, T_J = 25 °C	
Q_{rr}	Reverse Recovery Charge	198		nC		
I_{rrm}	Peak Reverse Recovery Current	39		A		
t_{rr}	Reverse Recover time	13		ns	V_{GS} = -4 V, I_{SD} = 13.4 A, V_R = 500 V di_F/dt = 1900 A/µs, T_J = 25 °C	
Q_{rr}	Reverse Recovery Charge	95		nC		
I_{rrm}	Peak Reverse Recovery Current	14		A		

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	0.88	1.14	°C/W		Fig. 21

Typical Performance

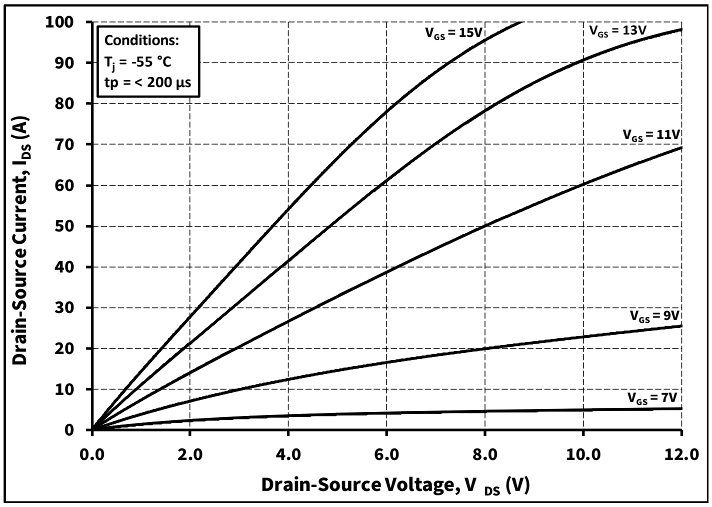


Figure 1. Output Characteristics T_J = -55 ºC

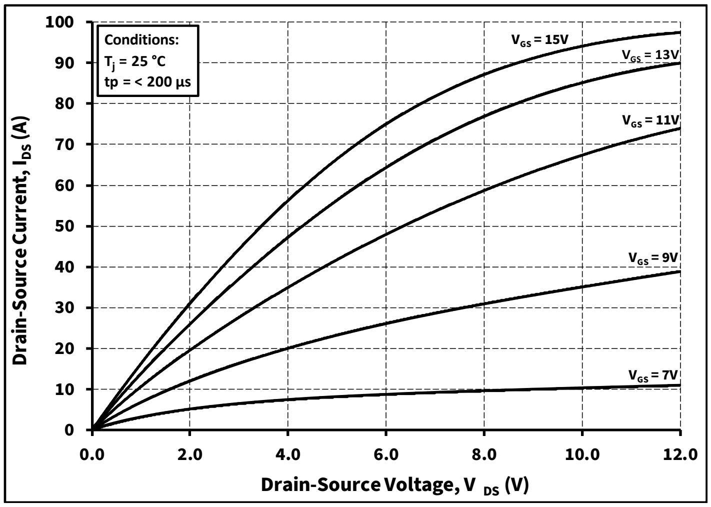


Figure 2. Output Characteristics T_J = 25 ºC

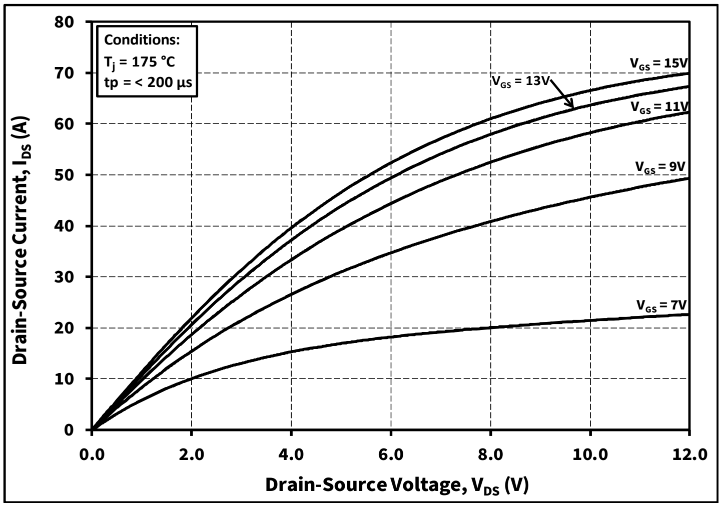


Figure 3. Output Characteristics T_J = 175 ºC

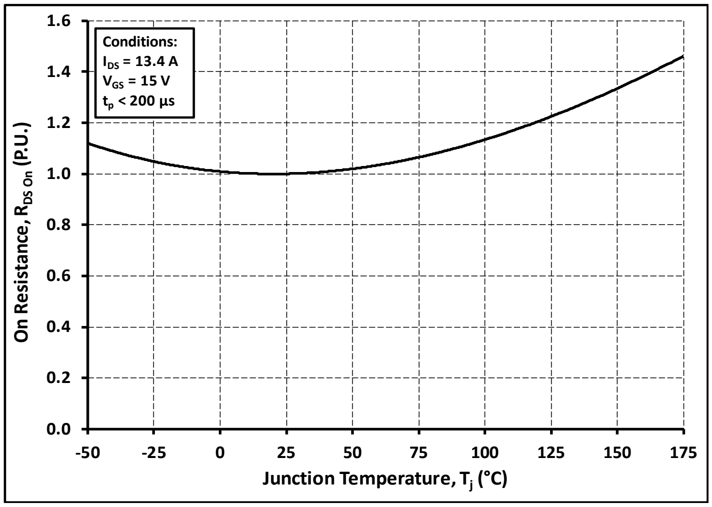


Figure 4. Normalized On-Resistance vs. Temperature

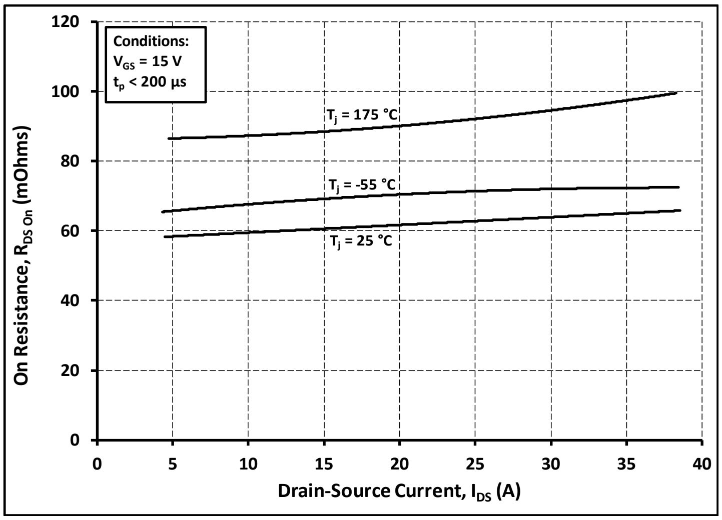


Figure 5. On-Resistance vs. Drain Current
For Various Temperatures

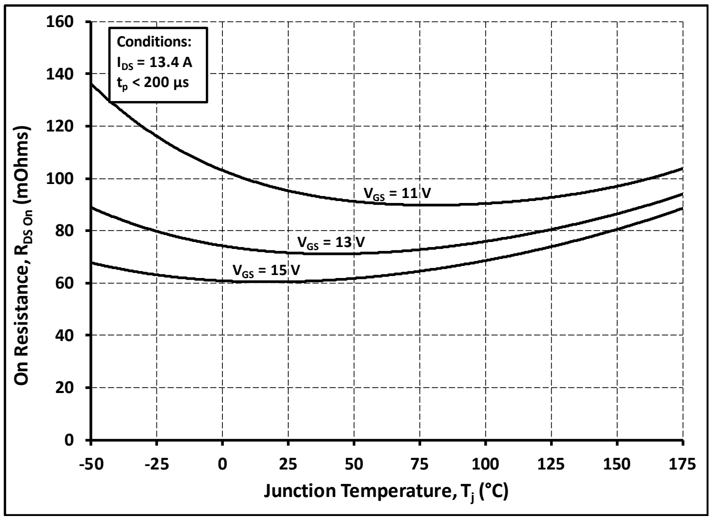


Figure 6. On-Resistance vs. Temperature
For Various Gate Voltage

Typical Performance

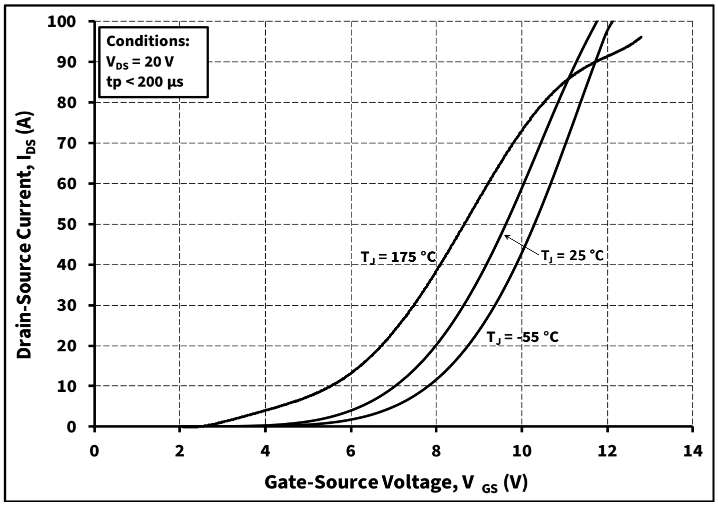


Figure 7. Transfer Characteristic for Various Junction Temperatures

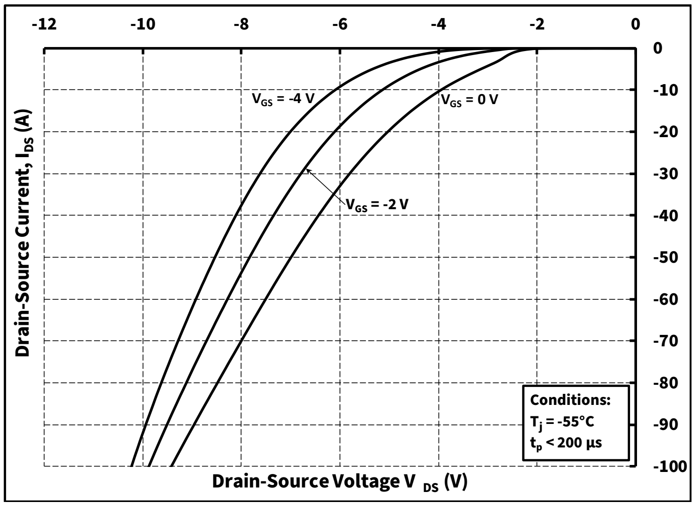


Figure 8. Body Diode Characteristic at -55 °C

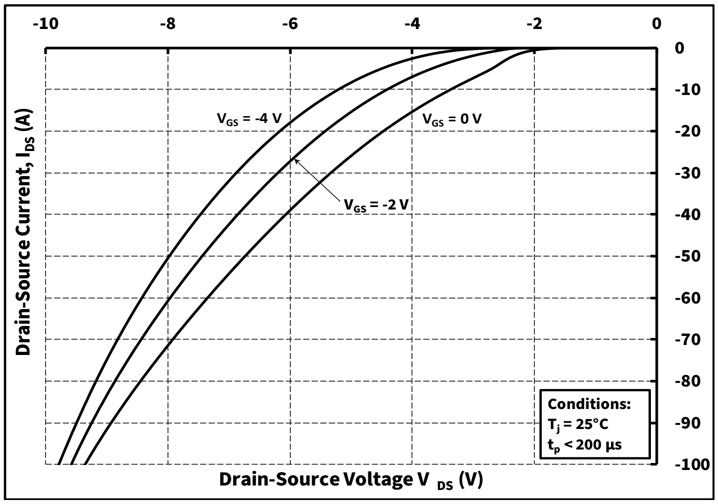


Figure 9. Body Diode Characteristic at 25 °C

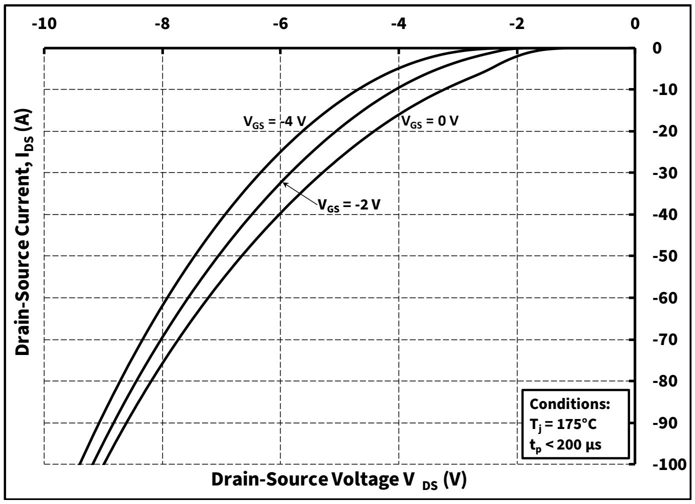


Figure 10. Body Diode Characteristic at 175 °C

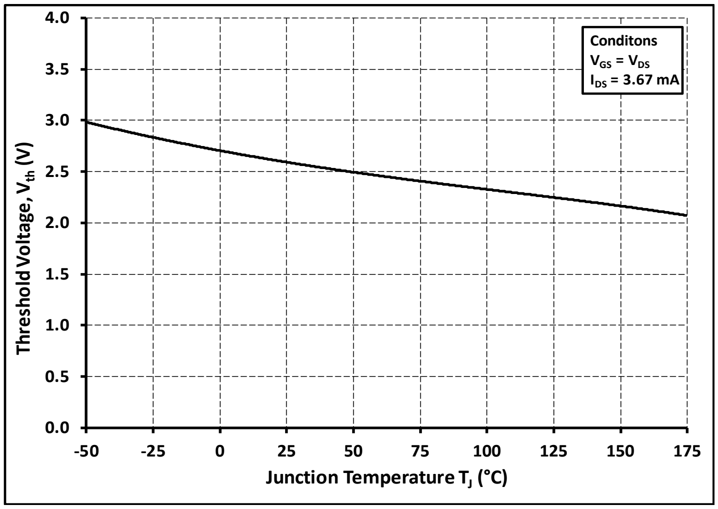


Figure 11. Threshold Voltage vs. Temperature

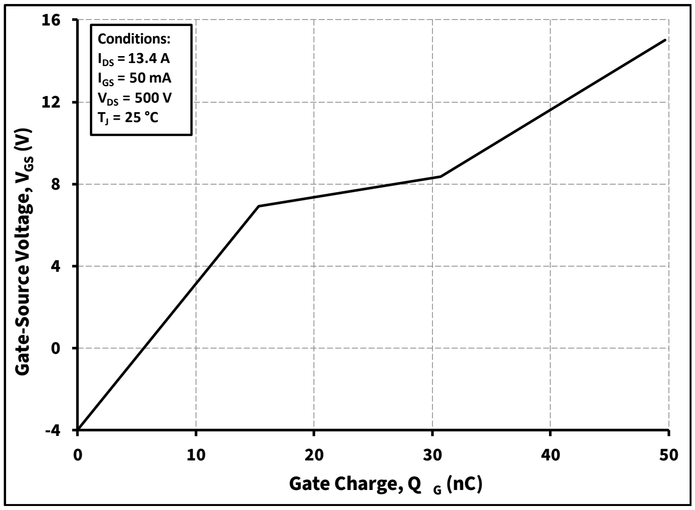


Figure 12. Gate Charge Characteristics

Typical Performance

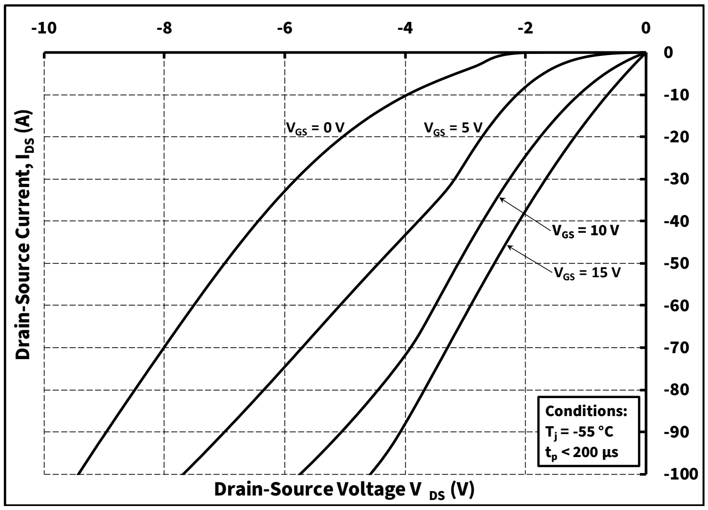


Figure 13. 3rd Quadrant Characteristic at -55 °C

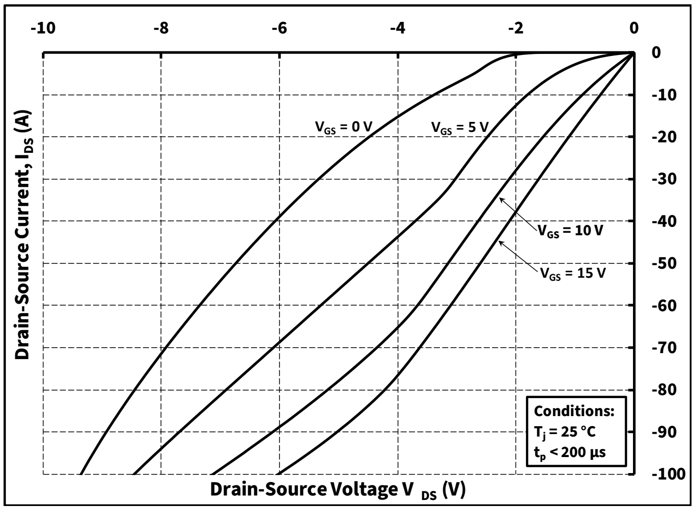


Figure 14. 3rd Quadrant Characteristic at 25 °C

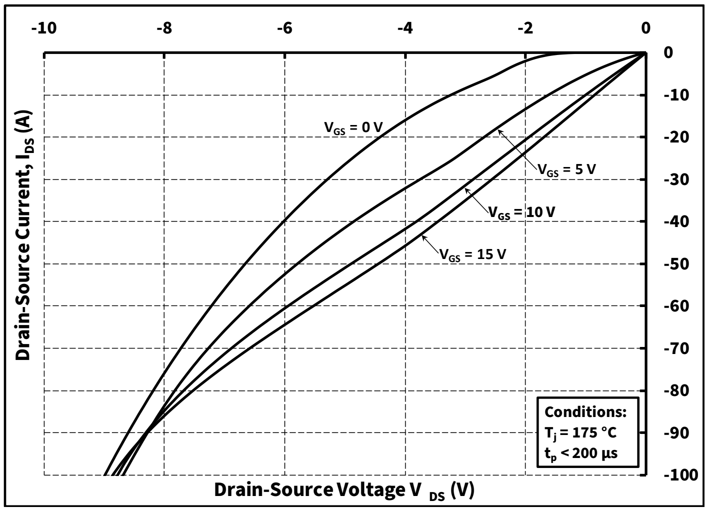


Figure 15. 3rd Quadrant Characteristic at 175 °C

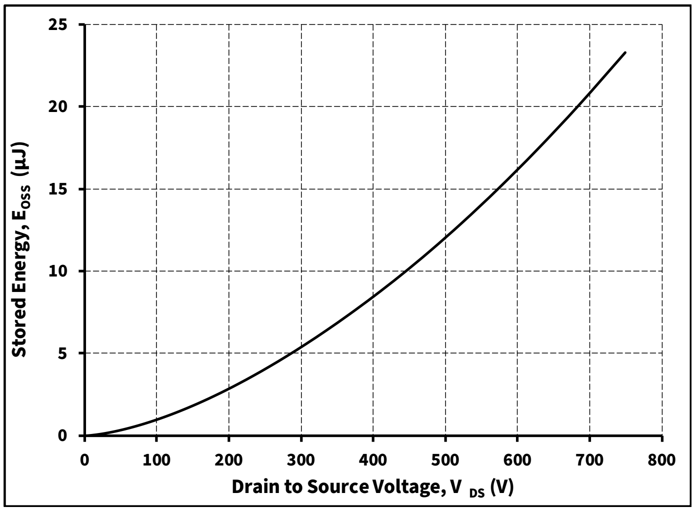


Figure 16. Output Capacitor Stored Energy

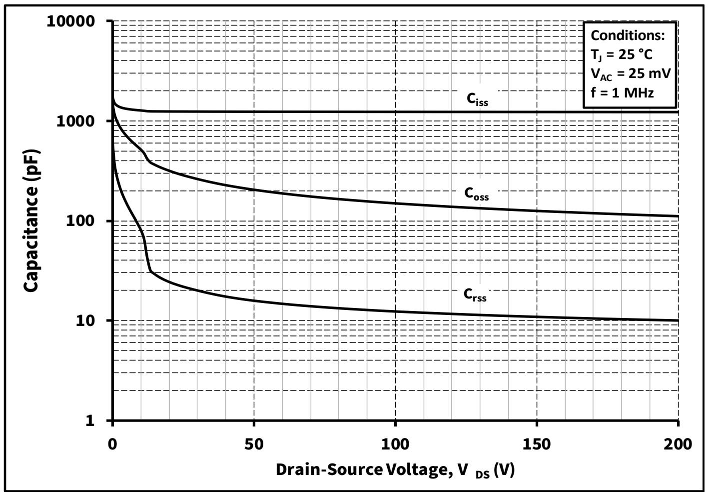


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200V)

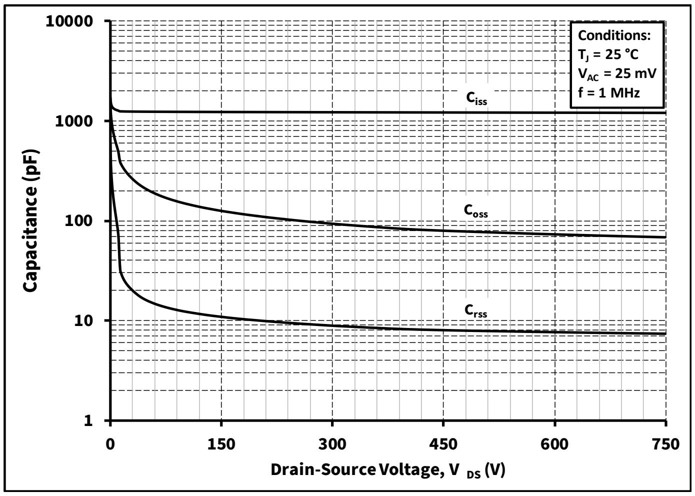


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 750V)

Typical Performance

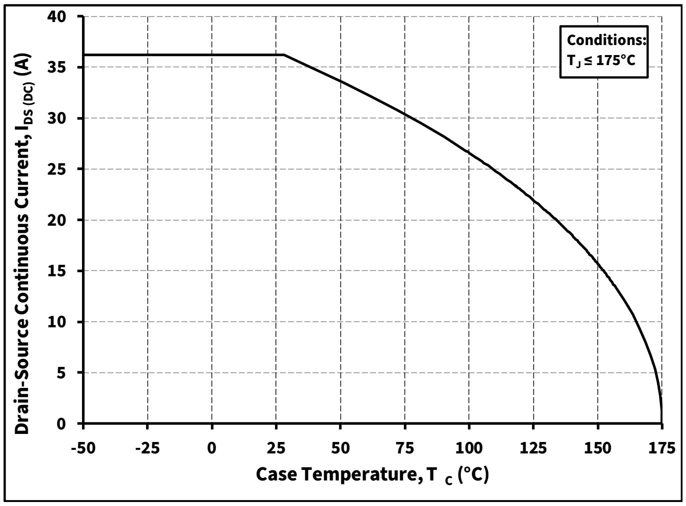


Figure 19. Continuous Drain Current Derating vs. Case Temperature

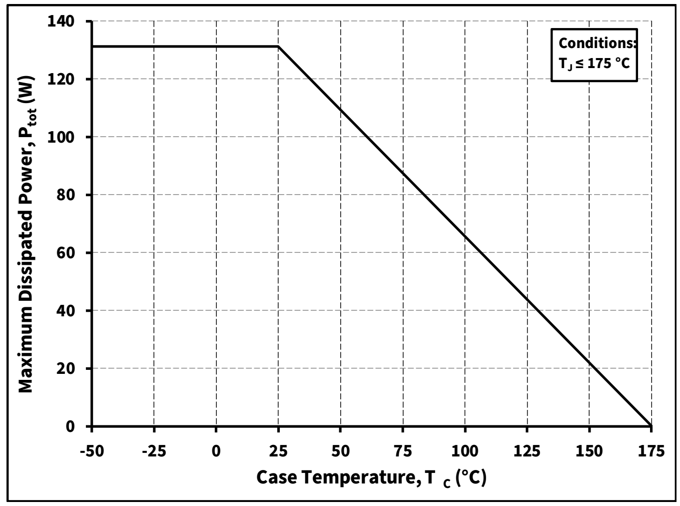


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

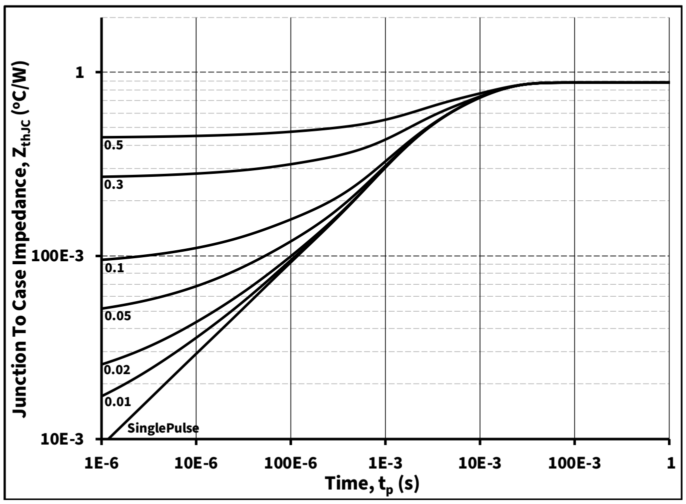


Figure 21. Transient Thermal Impedance (Junction - Case)

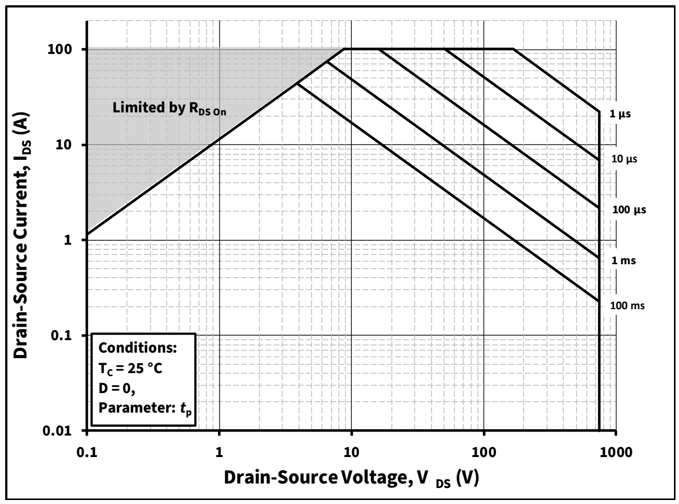


Figure 22. Safe Operating Area

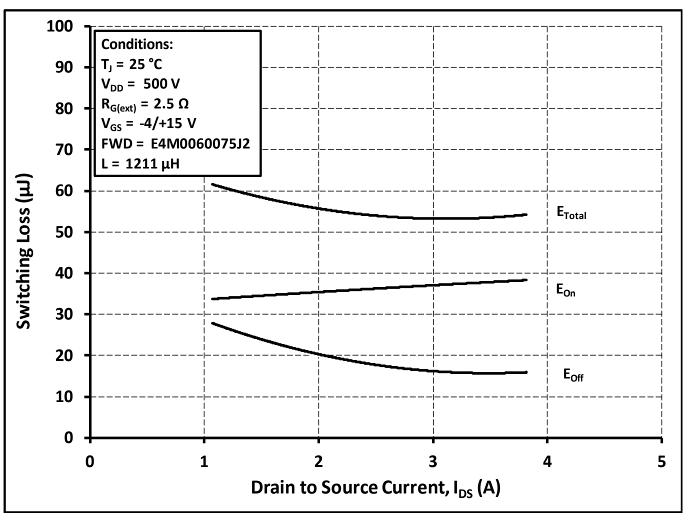


Figure 23. Clamped Inductive Switching Energy vs. Low Drain Current (V_{DD} = 500V)

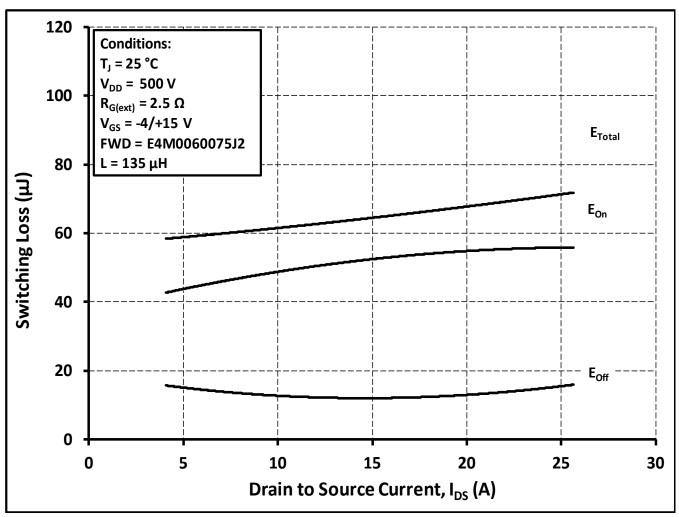


Figure 24. Clamped Inductive Switching Energy vs. Drain Current (V_{DD} = 500V)

Typical Performance

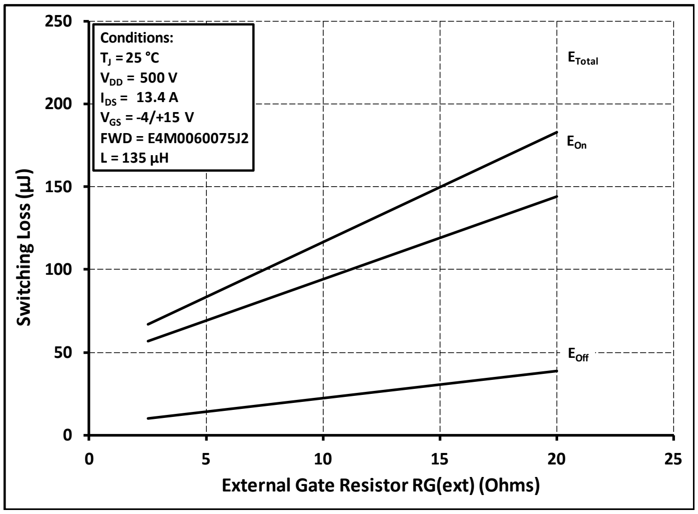


Figure 25. Clamped Inductive Switching Energy vs. $R_{G(ext)}$

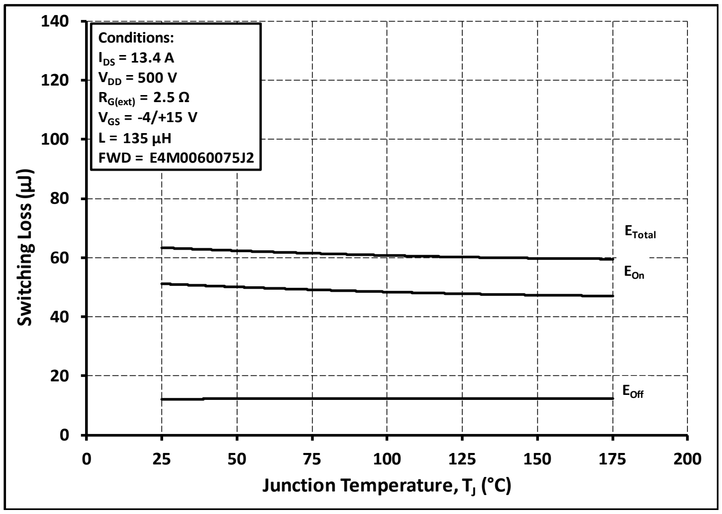


Figure 26. Clamped Inductive Switching Energy vs. Temperature

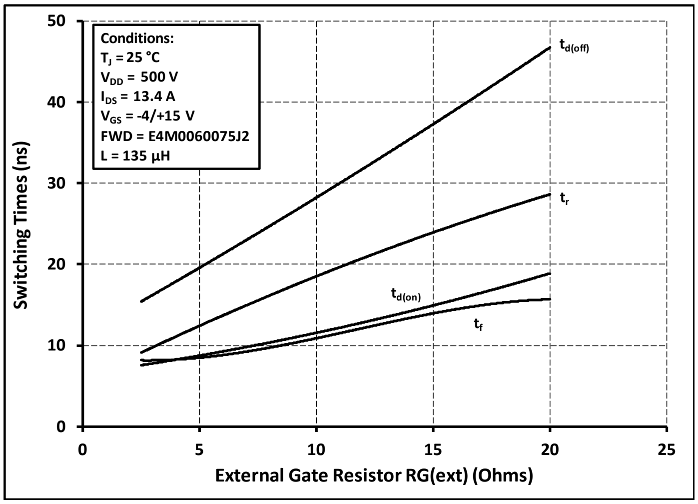


Figure 27. Switching Times vs. $R_{G(ext)}$

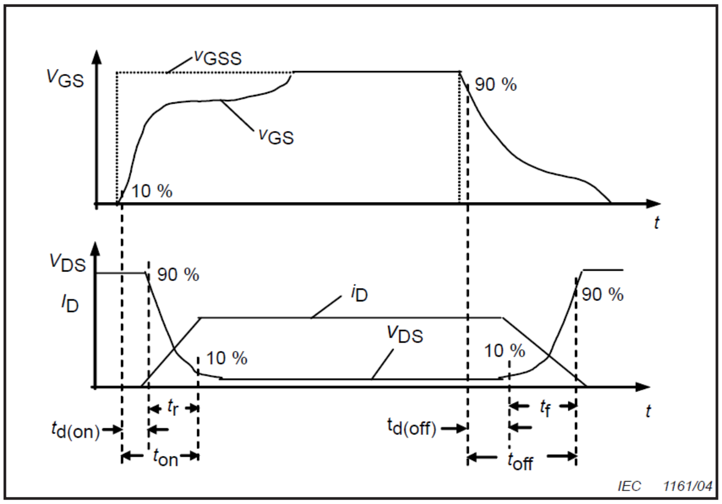


Figure 28. Switching Times Definition

Test Circuit Schematic

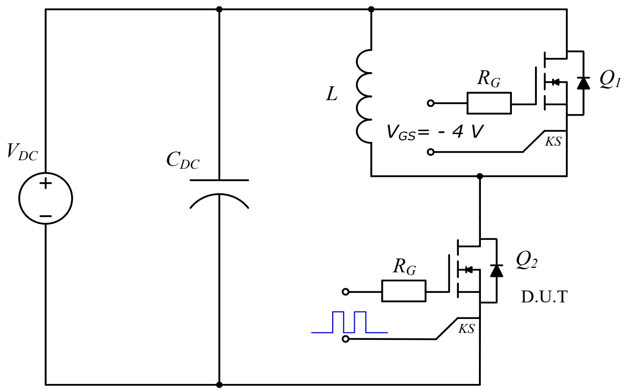
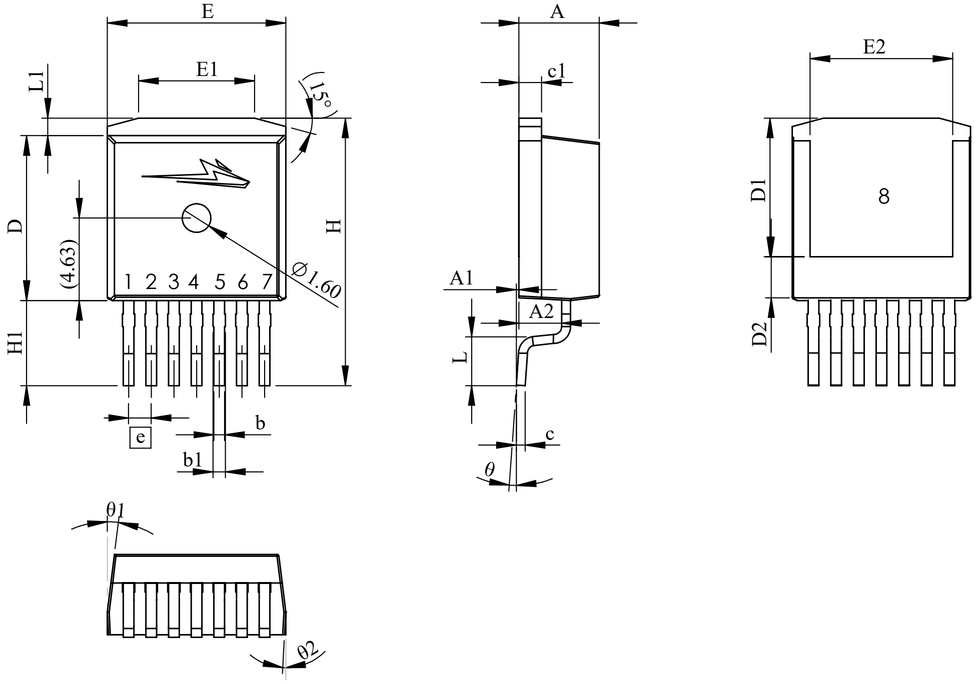


Figure 29. Clamped Inductive Switching Waveform Test Circuit

Package Dimensions



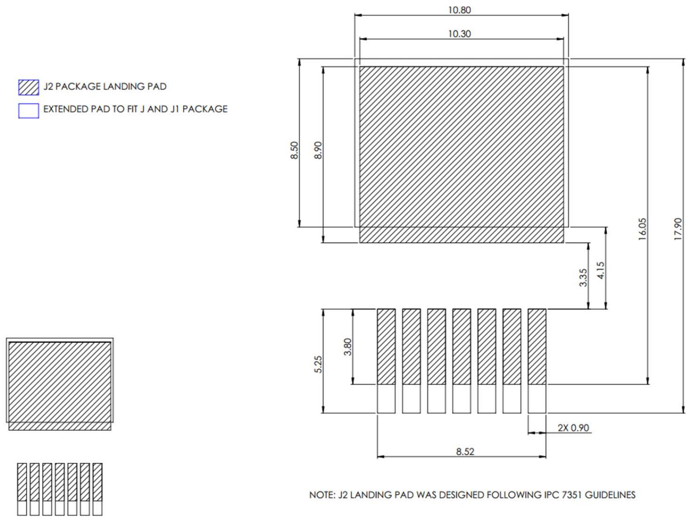
SYMBOL	MIN (mm)	MAX (mm)
A	4.30	4.70
A1	0.00	0.25
A2	2.20	2.60
b	0.52	0.72
b1	0.60	0.80
c	0.42	0.62
c1	1.07	1.47
D	9.05	9.45
D1	7.58	7.98
D2	2.05	2.45
E	9.80	10.20
E1	6.30	6.97
E2	7.80	8.20
e	1.27 BSC	
H	14.87	15.27
H1	4.55	4.95
L	2.48	2.88
L1	0.87	1.27
θ	0°	8°
θ1	4°	10°
θ2	0°	6°

1	GATE
2	KELVIN
3	SOURCE
4	
5	
6	
7	
8	DRAIN

NOTE
1. ALL METAL SURFACES ARE TIN PLATED (MATTE), EXCEPT AREA OF CUT.
2. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
3. ALL DIMENSIONS ARE LISTED IN MILLIMETERS. ANGLES ARE IN DEGREES.
4. PACKAGE BURR FLASH SIZE (0.5 mm) IS NOT INCLUDED IN THE DIMENSIONS

Recommended Solder Pad Layout

All dimensions in mm



Revision history

Document Version	Date of release	Descriptiion of changes
1.0	March 2024	Initial release
2	January - 2025	Legal Disclaimer Updated

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